Specifications for Approval

	Customer Part	No.:		
	Inhere Part No	.: PLC-LE-RGB-ADA		
	Part Name: 35	28 全彩 LED		
	Spec Issue Date	e: 2016-03-11		
	Revision No.: A	A		
======	=======================================		:===========	
l	.akeView			
\ \ /	e submit herewith the followi	ing information for your an	oroval:	
•		Inspection Record	■ LED Dimension	
	■ Electrical Characteristics Cu	•	rcuit Diagram	
	■ Soldering recommendation		ū	
D	repared by: Lily	Checked by: Tom	Approved by: James	
	Pate: 2016-03-11	Date: 2016-03-11	Date: 2016-03-11	
======	=======================================			
Cı	ıstomer Opinion			
	Approve and no objection			
	Reject with the following rea	ason:		

SPECIFICATIONS

Features

- 3.5mm x 2.8mm TOP LED, 1.8mm thickness.
- Low power consumption.
- Wide view angle.
- Package: 2,000pcs/reel.
- RoHS compliant.

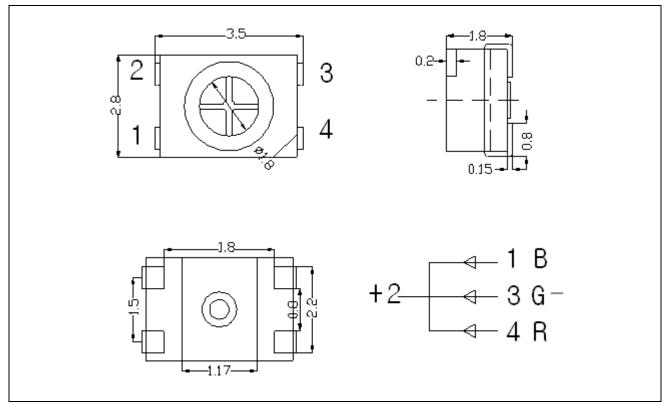
Description

- The Red source color devices are made with AlGaInP on GaAs Light Emitting Diode.
- The Green source color devices are made with InGaN/GaN on Al₂O₃ Light Emitting Diode.
- The Blue source color devices are made with InGaN/GaN on Al₂O₃ Light Emitting Diode

Applications

- Ideal for back light and indicator.
- Various colors and lens types available.

Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

Selection Guide

Part No. Dice Emitting Color Le			Lens Type	I	Viewing Angle(°)		
				Min.	Тур.	Max.	$2\theta_{\frac{1}{2}}$
S3528QPRGBT-009	AlGaInP	Red	Water Clear	200	400		130
	InGaN/GaN	Green		1000	2000		
	InGaN/GaN	Blue		300	500		

Note:

- $1.\, heta_{rac{1}{2}}$ is the angle from optical centerline where the luminous intensity is $\,rac{1}{2}\,$ the optical centerline value.
- 2. The tolerance of luminous intensity (Iv)is $\pm 15~\%$.

Electrical / Optical Characteristics (at $T_a = 25$ °C)

Damanatan	Symbol	Color	Value				o . tiv	
Parameter			Min.	Тур.	Max.	Unit	Test Condition	
		Red	1.8		2.4	V		
Forward Voltage	$V_{\rm F}$	Green	2.8		3.4		I _F = 20mA	
		Blue	2.8		3.4			
	λ _D	Red	620		630	nm	I _F = 20mA	
Dominant Wavelength		Green	518		523			
		Blue	465		475			
		Red						
Reverse Current	I_R	Green			10	μΑ	$V_R = 5V$	
		Blue						

Note:

- 1. The tolerance of dominant wavelength is ±1nm.
- 2. The tolerance of forward voltage is \pm 0.05V.
- 3. This specification is a standard specification of our factory, can make in accordance with customer's special requirement.

Absolute Maximum Ratings (at T_a = 25°C)

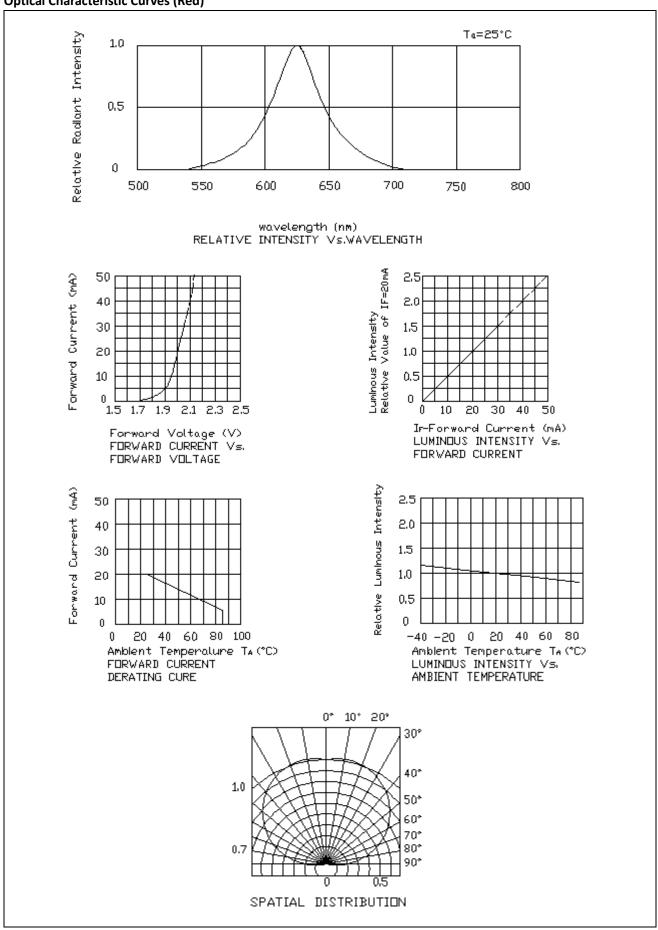
Davarrator	Complete	Value			ll-it	
Parameter	Symbol	R	G	В	Unit	
Power Dissipation	P_{D}	72 102 102		102	mW	
Pulse Forward Current(Duty 1/10 @ 1 kHz)	I_{FP}	100		100 mA		mA
Forward Current	I_{F}	30		30 mA DC		
Reverse Voltage	V_R	5		5 V DC		
Operating Temperature	$T_{ m opr}$	-40 ~ +85		-40 ~ +85 °C		
Storage Temperature	$T_{ m stg}$	-40 ~ +85		-40 ∼ +85 °C		
Soldering Temperature	T _{sol}	260℃ for 5 sec				

Reliability Testing Conditions

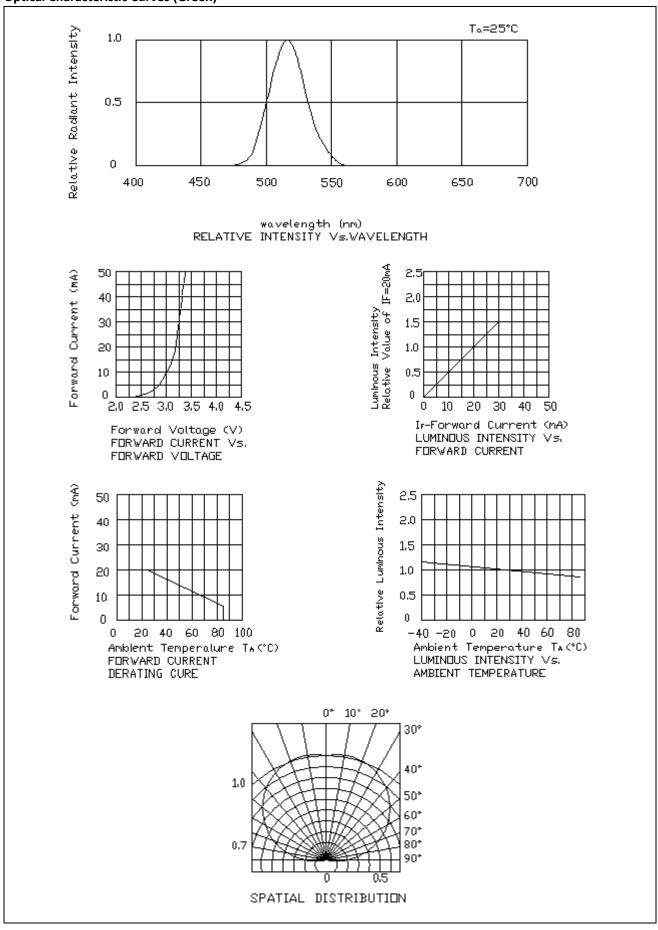
NO	Test Item	Test Conditions	Duration	Sample	Ac/Re
1	Temperature Cycle	-40°C±5°C∼25°C±5°C∼100°C±5°C∼25°C±5°C 30min 5min 30min 5min	100cycles	22	0/1
2	High Temp. Storage	Ta=100°C ±5°C	1000hours	22	0/1
3	Temp.& Humidity Test	Ta=85℃±5℃ RH=85%±5%	1000hours	22	0/1
4	Low Temp. Storage	Ta=-40°C ±5°C	1000hours	22	0/1
5	Operating Life Test	Ta=25±5℃ DC IF=20mA	1000hours	22	0/1
6	Solder Heat	Tsol=260±5℃,5s	1times	22	0/1
7	Thermal Shock	-40±5°C →100±5°C 15min 15min	100cycles	22	0/1

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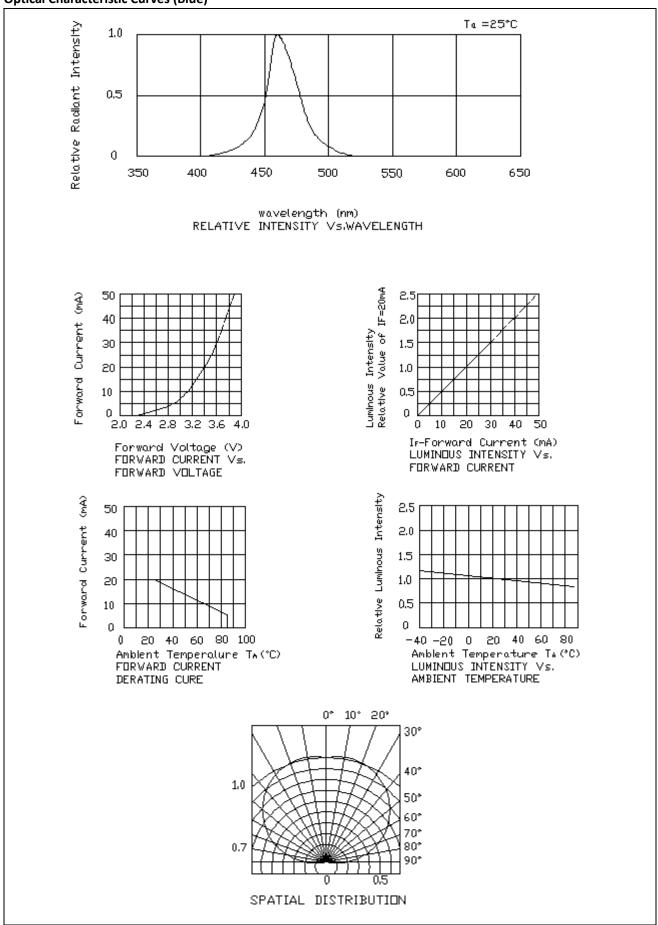
Optical Characteristic Curves (Red)



Optical Characteristic Curves (Green)



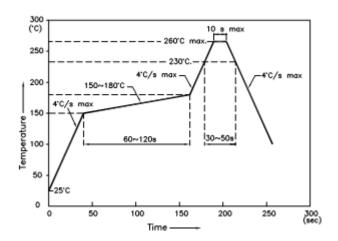
Optical Characteristic Curves (Blue)



Precautions in Use

Reflow Profile

■ Reflow Temp/Time



Notes:

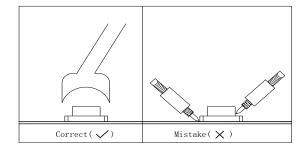
- 1. We recommend the reflow temperature 245 $^{\circ}$ C (±5 $^{\circ}$ C).the maximum soldering temperature should be limited to 260 $^{\circ}$ C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260 $^{\circ}$ C. If temperature is higher, time should be shorter (+10 $^{\circ}$ C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable . Surface temperature of the device should be under 230 $^{\circ}$ C .

■Rework

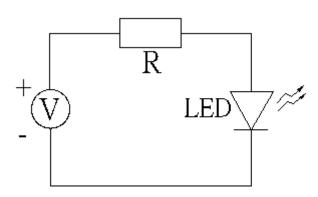
- 1. Customer must finish rework within 5 sec under 260 °C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



- 1. Customer must finish rework within 5 sec under 260℃.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max. Temperature : 5° C $^{\sim}$ 30 $^{\circ}$ C

2.2 Shelf life in sealed bag: 12 month at $<5^{\circ}\text{C}^{\sim}30^{\circ}\text{C}$ and <30% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at \leq 20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs.

The Conditions are as followings:

- 3.1 $60\pm3\,^{\circ}\mathrm{C}\,$ x(12~24hrs) and <5%RH, taped reel type
- 3.2 $100\pm3^{\circ}$ C x(45min~1hr), bulk type
- 3.3 130 ± 3 °C x(15~30min), bulk type